

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S1	7	semiconductor adj substrate and organic adj substrate and pad and solder and ("coefficient of thermal expansion" or cte)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/09/10 09:08
S2	6	("5471090"   "6005292"   "6046910"   "6118181"   "6232668"   "6271597").PN.	USPAT	OR	ON	2002/11/05 12:59
S3	0	"6310403".URPN.	USPAT	OR	ON	2002/11/05 13:02
S4	6	("5471090"   "6005292"   "6046910"   "6118181"   "6232668"   "6271597").PN.	USPAT	OR	ON	2002/11/05 13:02
S5	9	("3842189"   "4056681"   "4647959"   "4949148"   "5214308"   "5302854"   "5331513"   "5528461"   "5657207").PN.	USPAT	OR	ON	2002/11/05 13:02
S6	5	"6046910".URPN.	USPAT	OR	ON	2002/11/05 13:03
S7	4345	"coefficient of thermal expansion" or cte	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2002/11/05 13:16
S8	31	((257/786).CCLS.) and ("coefficient of thermal expansion" or cte)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2002/11/05 13:06
S9	1299	c4 same solder	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2002/11/05 13:07
S10	169	("coefficient of thermal expansion" or cte) and (c4 same solder)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2002/11/06 13:55
S11	327	gigapascal	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2002/11/05 13:16
S12	19	("coefficient of thermal expansion" or cte) and gigapascal	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2002/11/05 13:18

S13	0	underfill adj material same gigapascal	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2002/11/05 13:19
S14	775	underfill adj material	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2002/11/05 13:19
S15	188	("coefficent of thermal expansion" or cte) and (underfill adj material )	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2002/11/05 13:19
S16	143	conductive adj pad and solder and bump and c4	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2002/11/05 13:41
S17	1235	(257/786).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2002/11/06 09:10
S18	195	c4 and solder and ("coefficent of thermal expansion" or cte)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2002/11/06 13:51
S19	7841	(lead adj base adj solder) or (lead-tin) or (pb adj sn or pbsn)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2002/11/06 14:46
S20	20	("coefficent of thermal expansion" or cte) and (c4 same solder) and ((lead adj base adj solder) or (lead-tin) or (pb adj sn or pbsn))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2002/11/06 13:56
S21	2570	(lead adj base adj solder) or (lead-tin) or (pb adj sn or pbsn) and c4	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2002/11/06 15:00
S22	14566	flip adj chip or flipchip	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2002/11/06 14:47

S23	386	((lead adj base adj solder) or (lead-tin) or (pb adj sn or pbsn) and c4) and (flip adj chip or flipchip)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2002/11/06 14:47
S24	245	((lead adj base adj solder) or (lead-tin) or (pb adj sn or pbsn)) and c4	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2002/11/06 15:01
S25	69	larger near pad and smaller near pad and solder	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2003/11/11 10:14
S26	6	("4673772"   "5616520"   "5761048"   "5859407"   "5907187"   "6093964").PN.	USPAT	OR	ON	2003/11/11 10:23
S27	1	"6285083".URPN.	USPAT	OR	ON	2003/11/11 10:25
S28	2	"6274474".URPN.	USPAT	OR	ON	2003/11/11 10:32
S29	0	beriner.in.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2003/11/18 13:41
S30	670	bernier.in.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2003/11/18 13:41
S31	7	solder adj ball and bernier.in.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2003/11/18 13:43
S32	6925	carey.in. or gramatzki.in. or homa.in. or langevin.in. or tran.in. or "white.in"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2003/11/18 13:44
S33	20	solder adj ball and (carey.in. or gramatzki.in. or homa.in. or langevin.in. or tran.in. or "white.in")	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2003/11/18 13:45
S34	57	"5075965".URPN.	USPAT	OR	ON	2003/11/18 13:50
S35	0	"6330967".URPN.	USPAT	OR	ON	2003/11/18 13:54

S36	25	("4545610"   "5060844"   "5075965"   "5161729"   "5221038"   "5234152"   "5372298"   "5429292"   "5470787"   "5473814"   "5580668"   "5591941"   "5634268"   "5639696"   "5675889"   "5729896"   "5796591"   "5808853"   "5825629"   "5912505"   "5953623"   "5965945"   "6121069"   "6130476"   "6162660").PN.	USPAT	OR	ON	2003/11/18 13:54
S37	27	organic adj substrate and (bump or electrode or pad) and solder adj ball and semiconductor adj substrate	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/09/03 14:30
S38	2	("5889326").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/09/10 09:16
S39	9	("4724472"   "4970570"   "5028987"   "5422516"   "5508561"   "5611481"   "5640051"   "5640052"   "5641113").PN.	USPAT	OR	ON	2004/09/10 09:11
S40	27	"5889326".URPN.	USPAT	OR	ON	2004/09/10 09:12
S41	3540	((257/747) or (257/759) or (257/773) or (257/779)).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/09/10 09:17
S42	5624	organic adj substrate	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/09/10 09:17
S43	60	((((257/747) or (257/759) or (257/773) or (257/779)).CCLS.) and (organic adj substrate)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/09/10 09:28
S44	113	(257/474).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/09/10 09:29

S45	256	(257/747).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/09/10 09:29
S46	143	pad adj size and semiconductor adj die	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/10 09:32
S47	2	organic adj substrate and S46	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/10 09:32
S48	10	("6166556").URPN.	USPAT	OR	ON	2004/12/10 09:41